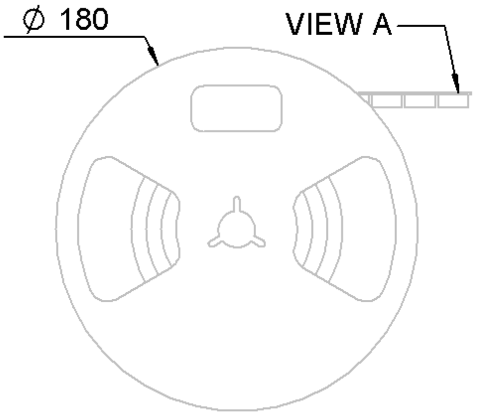
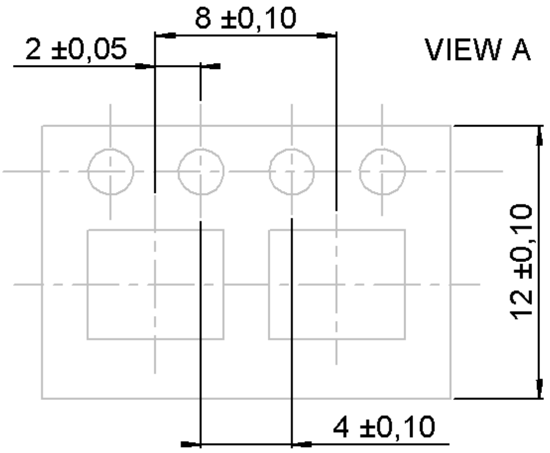
RIGHT ANGLE H3 RECEPTACLE SMT TYPE

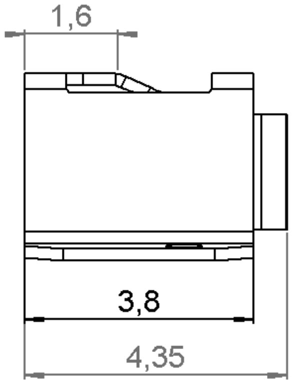
BOBINE 100

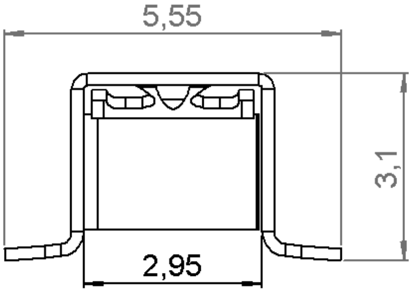
R107.303.040

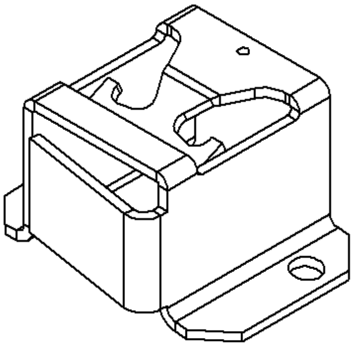
Series : **UMP**











SCALE: 1/1

All dimensions are in mm.

COMPONENTS	MATERIALS	PLATINGS (µm)
BODY	**BERYLLIUM COPPER**	**GOLD 0.2 OVER NICKEL 2**
CENTER CONTACT	-	-
OUTER CONTACT	-	-
INSULATOR	-	
GASKET	-	
OTHERS PARTS	-	-
-	-	-
-	-	-

RADIALL®

RIGHT ANGLE H3 RECEPTACLE SMT TYPE

BOBINE 100

R107.303.040

Series : **UMP**

PACKAGING

Standard	Unit	Other
100	**‘W’ option**	**Contact us**

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance		**50**	Ω
Frequency		**0-6**	GHz
VSWR	**1.05** +	**0,0300**	x F(GHz) Maxi
Insertion loss		**NA**	√F(GHz) dB Maxi
RF leakage	- (	**NA**	- F(GHz)) dB Maxi
Voltage rating		**100**	Veff Maxi
Dielectric withstanding voltage		**350**	Veff mini
Insulation resistance		**1000**	MΩ mini

ENVIRONMENTAL

Operating temperature	**-40/+125**	° C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

OTHERS CHARACTERISTICS

Assembly instruction

Others :

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	**-**	N mini
Axial force – Opposite end	**-**	N mini
Torque	**-**	N.cm mini
Recommended torque		
Mating	**-**	N.cm
Panel nut	**-**	N.cm
Mating life	**50**	Cycles mini
Weight	**0,0600**	g

Issue : 1213 C

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

RADIALL®

SOLDER PROCEDURE OF UMP RECEPTABLE IN INDUSTRIAL ENVIRONMENT

1. Deposit solder paste ‘Sn Ag4 Cu0.5’ on mounting zone by screen printing application. We recommend a low residue flux.
   We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.

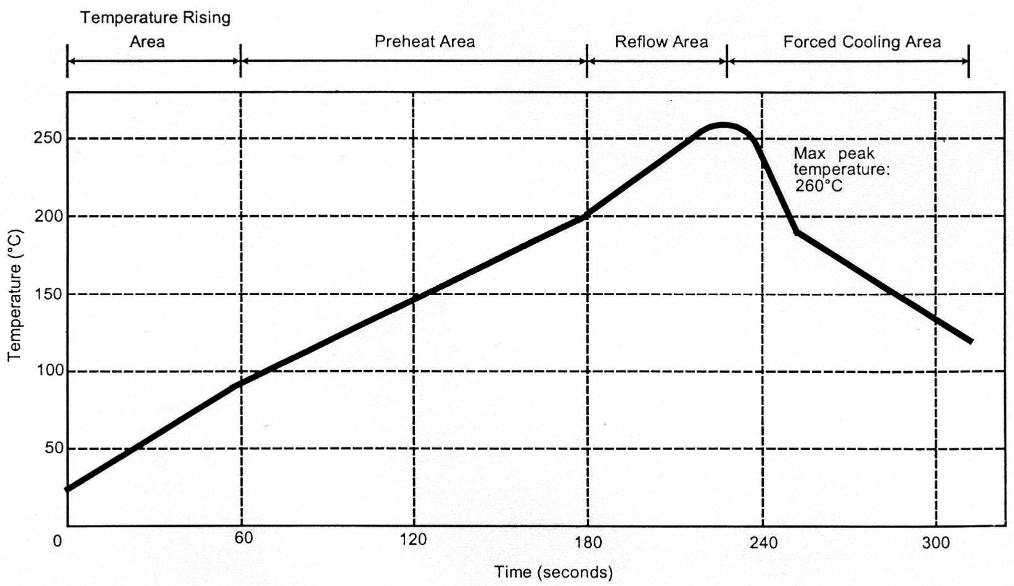
3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.

4. The cleaning of printed circuit boards is not obliged .

5. Verification of solder joints and position of the component by visual inspection.

NOTE : The UMP receptacle and the UMP plug must not be mated before completion of this procedure

TEMPERATURE PROFILE



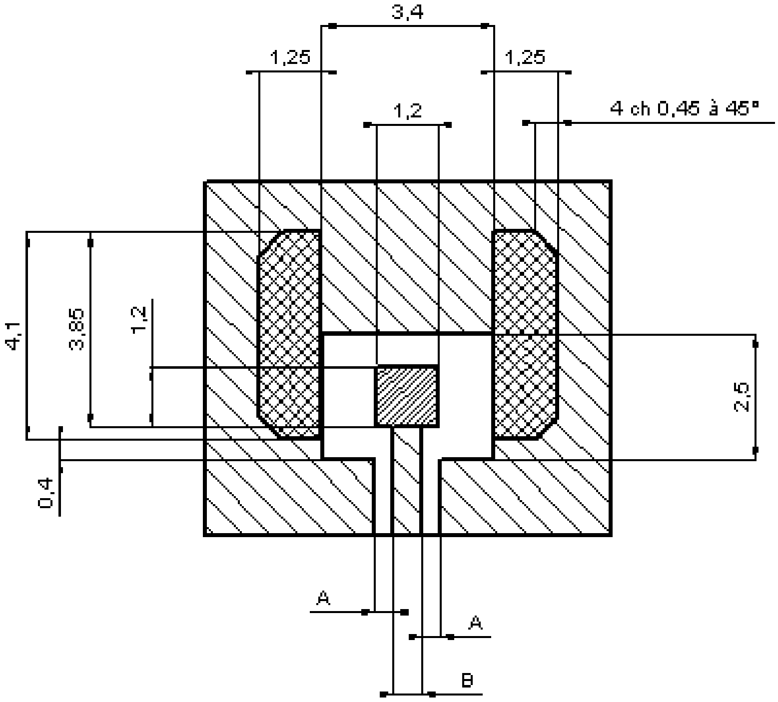
Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

UMP SERIES INFORMATION

PCB

COPLANAR LINE

Ground and signal are on the same side
The material of PCB is glass is glass-epoxy
Composite.



▦ Gold over nickel for solder paste

▨ Gold over nickel contact area free of any surface contaminant

▧ Ground + varnish

APPLICATION 75Ω
WITH B = 0,55mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,57
1,0	0,45
1,2	0,41
1,6	0,37

APPILCATION 50Ω
WITH B = 1,2mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,183
1,0	0,190
1,2	0,195
1,6	0,20

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

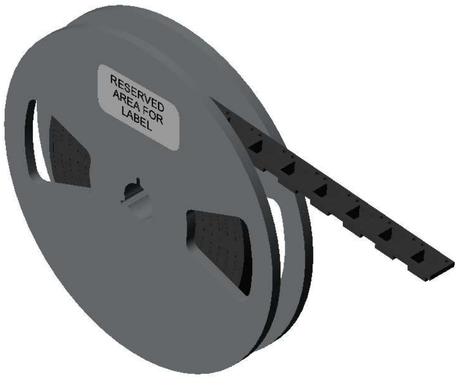
RIGHT ANGLE H3 RECEPTACLE SMT TYPE

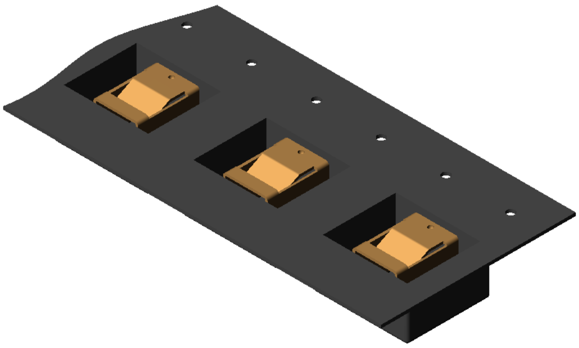
BOBINE 100

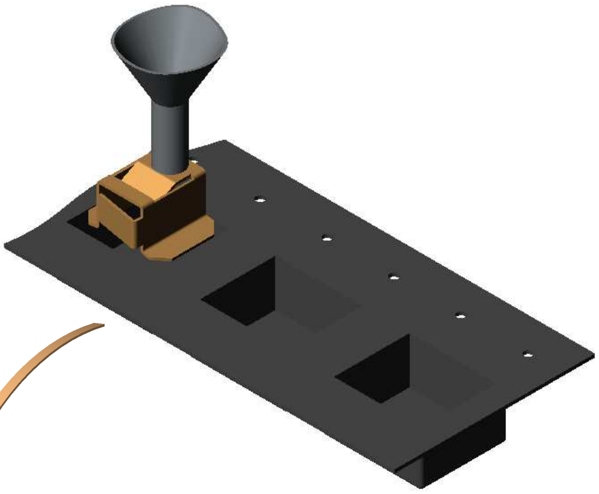
R107.303.040

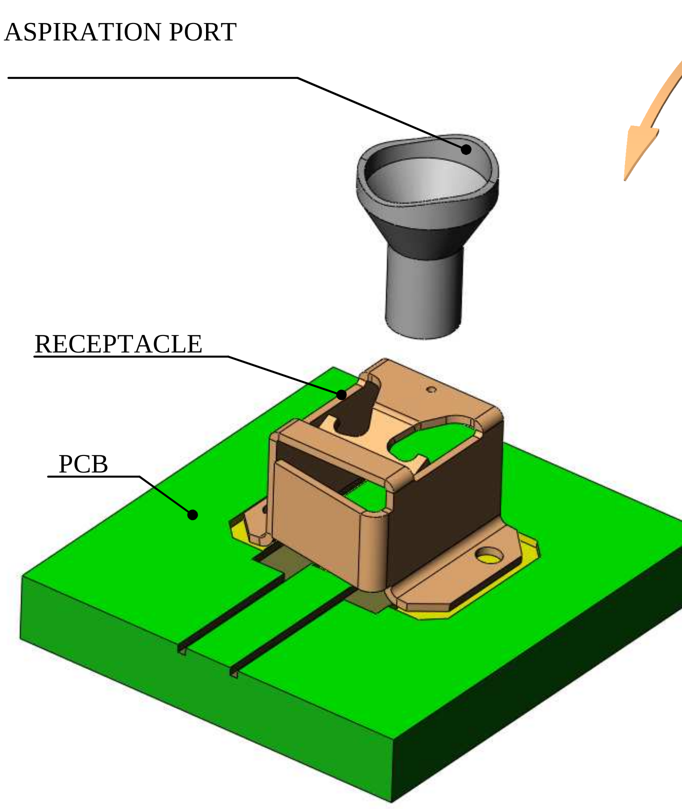
Series : **UMP**

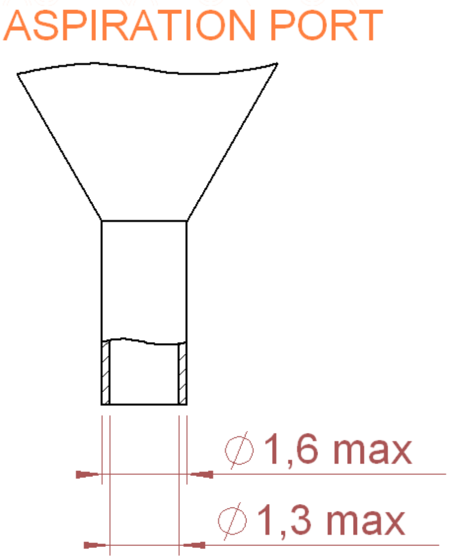
UMP SERIES INFORMATION









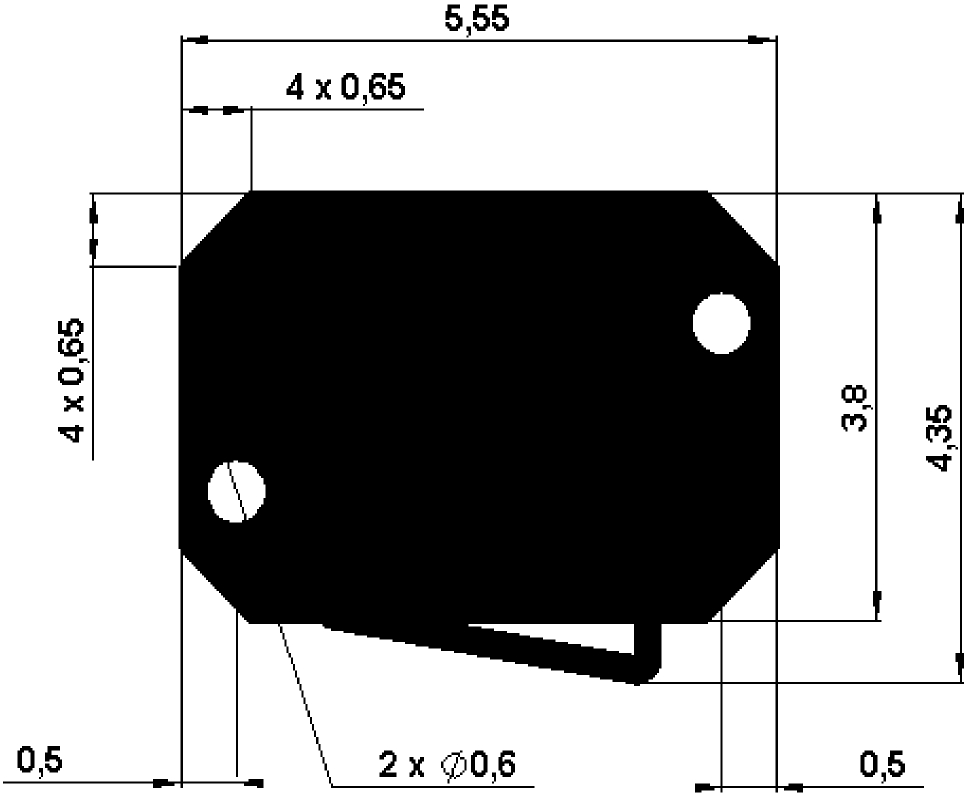


RIGHT ANGLE H3 RECEPTACLE SMT TYPE

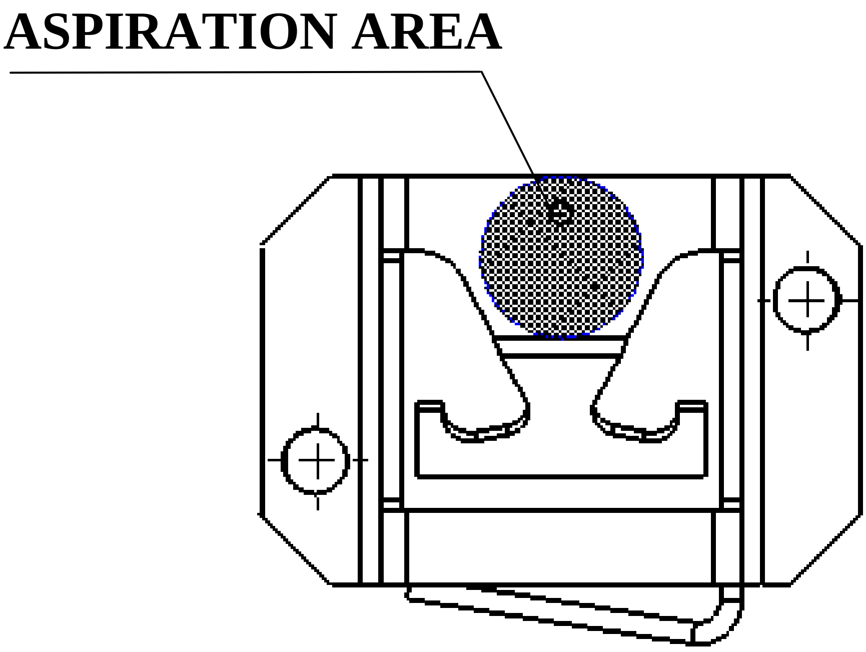
BOBINE 100

R107.303.040

Series : **UMP**



SHADOW FOR VIDEO CAMERA



In the effort to improve our products, we reserve the right to make changes judged to be necessary.

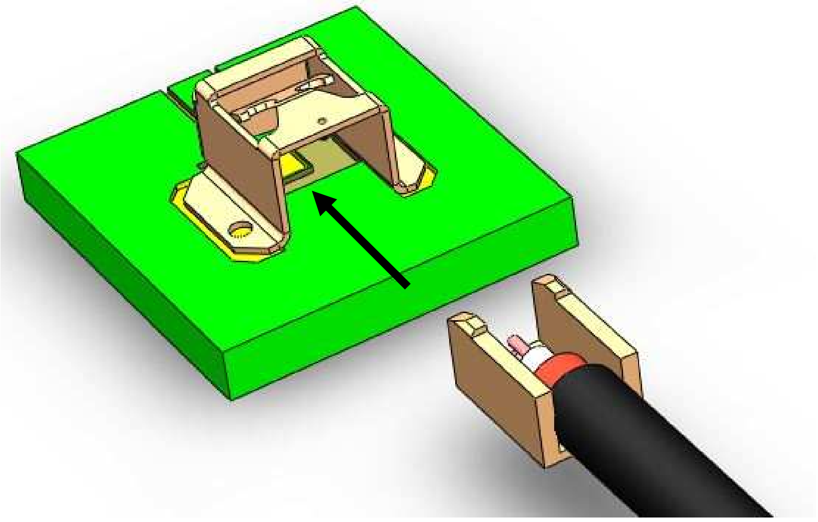
RIGHT ANGLE H3 RECEPTACLE SMT TYPE

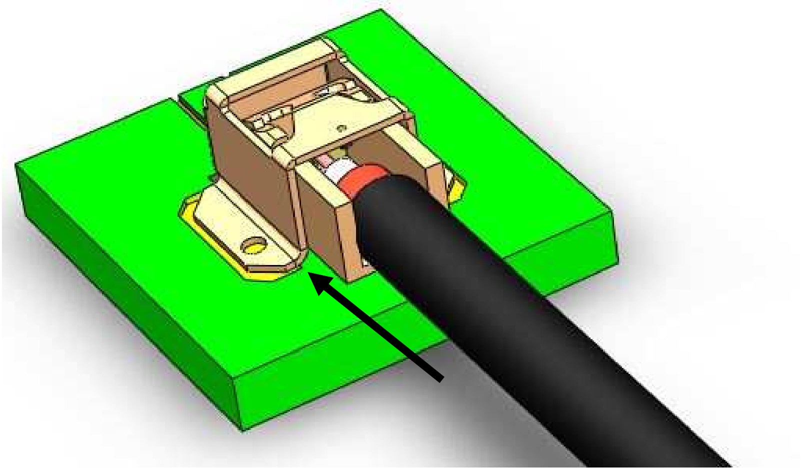
BOBINE 100

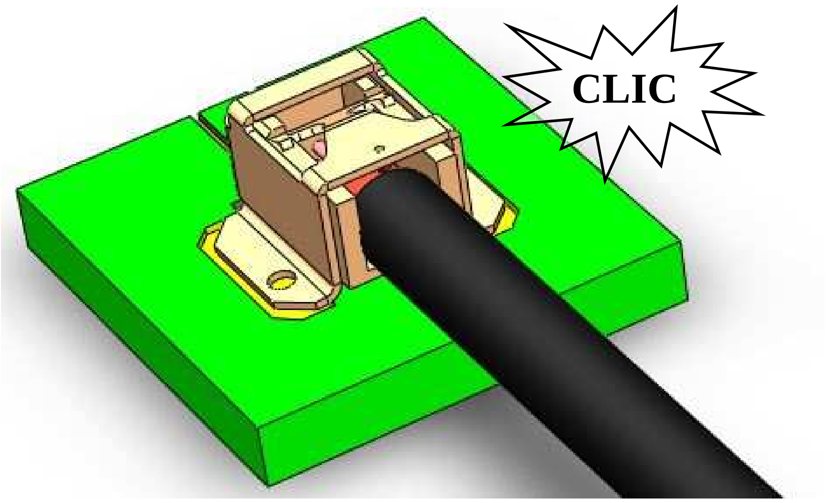
R107.303.040

Series : **UMP**

UMP CONNECTING NOTE







In the effort to improve our products, we reserve the right to make changes judged to be necessary.

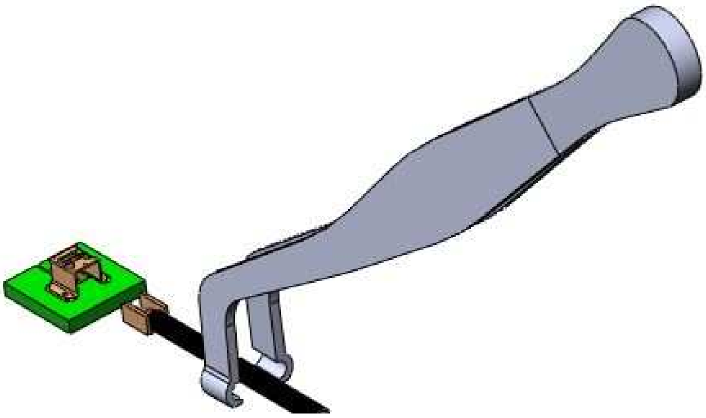
RIGHT ANGLE H3 RECEPTACLE SMT TYPE

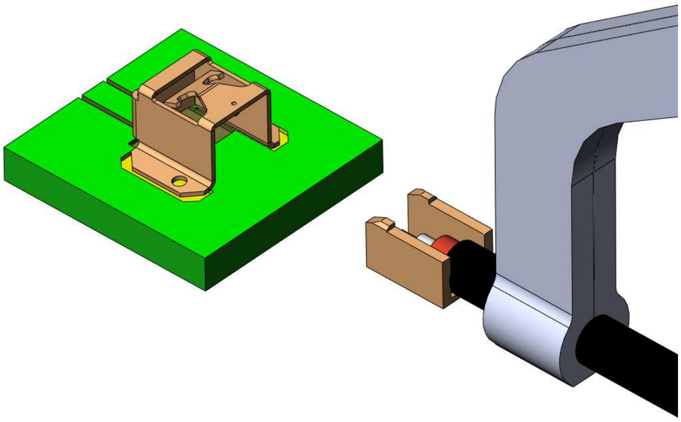
BOBINE 100

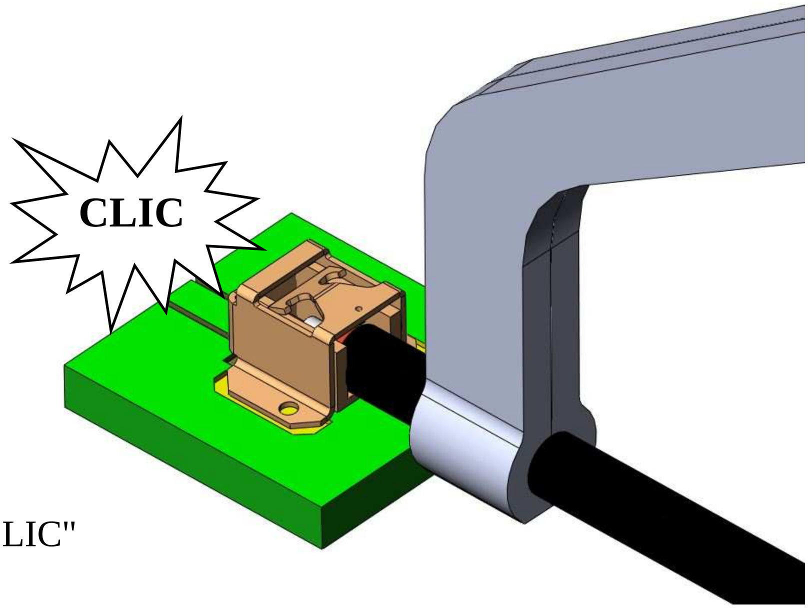
R107.303.040

Series : **UMP**

UMP CONNECTING NOTE







Do not push
Over the " CLIC"

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

RIGHT ANGLE H3 RECEPTACLE SMT TYPE

BOBINE 100

R107.303.040

Series : **UMP**

UMP DISCONNECTING NOTE